

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Peak pulse power ($t_p = 8/20\mu\text{s}$)	P_K	69	W
Peak pulse current ($t_p = 8/20\mu\text{s}$)	I_{PP}	5.5	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	± 30	KV
ESD according to IEC61000-4-2 contact discharge		± 30	
Junction temperature	T_J	150	
Storage temperature	T_{STG}	-55~+150	

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

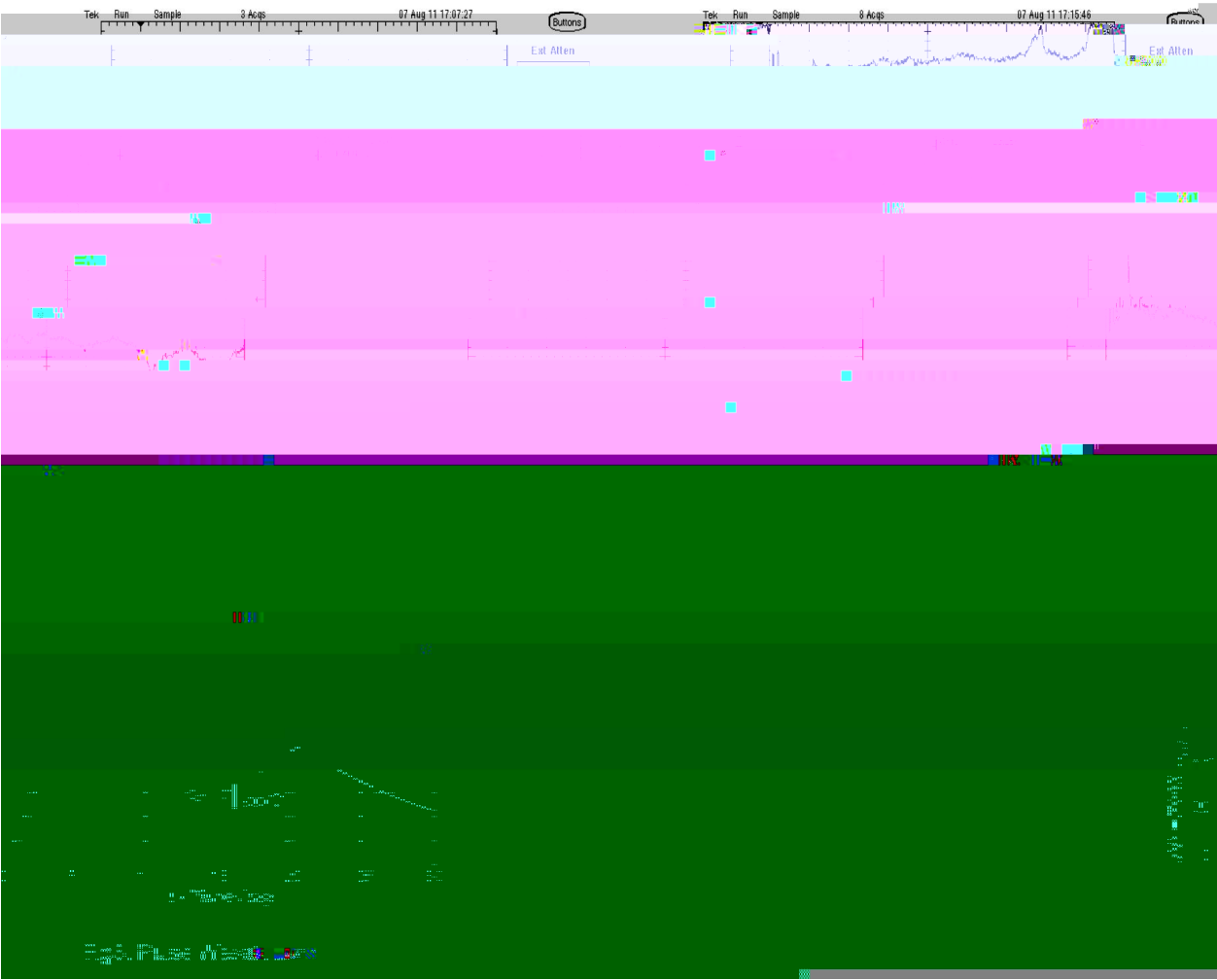
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse maximum working voltage	V_{RWM}				3.3	V
Reverse leakage current	I_R	$V_{RWM} = 3.3\text{V}$			0.1	μA
Reverse breakdown voltage ¹⁾	V_{BR}	$I_T = 1\text{mA}$	5.0		6.8	V
Clamping voltage ²⁾	V_C	$I_{PP} = 1\text{A}$ $t_p = 8/20\mu\text{s}$			9.8	V
		$I_{PP} = 5.5\text{A}$ $t_p = 8/20\mu\text{s}$			12.5	V
Junction capacitance	C_J	$V_R = 0\text{V}$ $f = 1\text{MHz}$			15	pF

Notes:

1) V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C .

2) Non-repetitive current pulse, according to IEC61000-4-5.

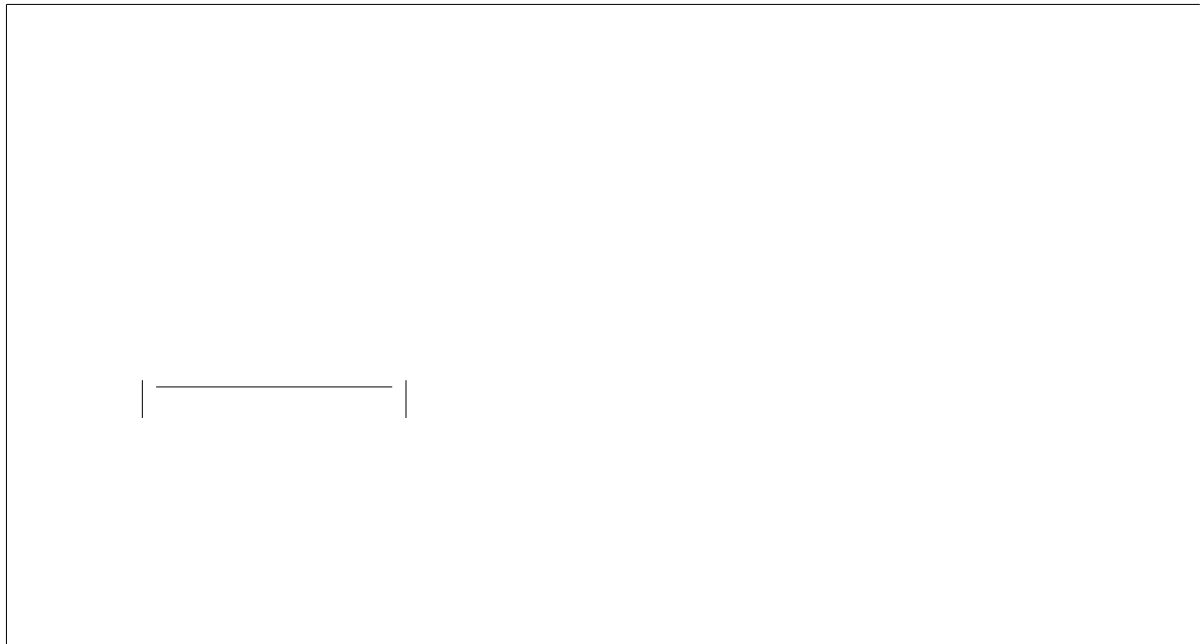
/ Electrical Characteristic Curve



/ Package Dimensions

DFN0603

Unit:mm



/ Marking Instructions



Note

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Product Type

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Lot No. Code,code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- Note:

1

150 180

60 90sec;

2

245 5

5 0.5sec;

3

2 10 /sec.
- 1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245 5 , Duration:5 0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

605 5